Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1607	257/734.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:18
L2	880	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:26
L3	1631	257/706.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:29
L4	833	257/720.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:33
L5	0	((semiconductor adj device) and (circuit adj board) and (heat adj spreader) and (low adj expansion adj material) and (SiC adj particles) and (mean adj grain adj size)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:35
S1	1	((heat adj (sink or spreader)) with ((low adj expansion) with material)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:38
S2	7	("5025347" "5844310" "5981085" "6129993" "6132676" "6381094" "6597574").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/19 19:29
S3	4	((heat adj (sink or spreader)) with ((low adj expansion) with material)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 19:41
S4	3533	((heat adj (sink or spreader)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 15:45
S5	2	"6753093"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 15:30

S6	7	("5025347" "5844310" "5981085" "6129993" "6132676" "6381094" "6597574").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/15 15:30
S7	319	S4 and ((heat adj (sink or spreader)) with (((silicon adj carb\$3) or SiC) and (aluminum or AL)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 15:46
S8	95	S7 and (circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:32
S9	25	S8 and (stress with (reduc\$4 or relie\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:12
S10	2	("6318442").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:34
S11	7	S8 and (auto or automobile)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:38
S12	872	S4 and (circuit adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:39
513	420	S12 and ((circuit adj board) with heat)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:39
S14	292	S13 and (heat with (chip or semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 16:40
S15	172	S14 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19

S16	16	S15 and tobita.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:18
S17	0	S16 and (low adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S18	0	S16 and (low with expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S19	93	S14 and (low with expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S20	74	S19 and stress	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 17:19
S21	19	("5006417").URPN.	USPAT	OR	ON	2005/09/15 17:24
S22	28	((heat adj (sink or spreader)) with ((low with expansion) with material)) and ((silicon adj carb\$3) or SiC) and (aluminum or AL)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:39
S23	61	((heat adj (sink or spreader)) with ((low with expansion) with material)) and ((heat adj (sink or spreader)) with (between and (chip or (semiconductor adj element))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:43
S24	31	S23 and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 11:43
S25	23	S24 and (metal with substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:21
S26	1415	257/734.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:18

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S27	819	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:26
S28	1376	257/706.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/12/08 19:28
S29	1025	257/717.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 21:27
S30	121	(low with expansion) and ((SiC or (silicon adj carbide)) with (grain and size)) and (Al or aluminum) and heat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/10 17:14
S31	21	S30 and (heat adj (spreader or sink))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 11:04
S32	1	S31 and (different with grain with size)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 11:05
S33	19	S31 and (grain with size)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 11:05
S34	12	S33 and heat.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 11:05
S35	12	S34 and ((SiC or (silicon adj carbide)) with (Al or aluminum))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 11:10

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S36	38	("20020023733" "3574580" "3678995" "3828848" "3872496" "3912500" "3913280" "3949263" "4231195" "4576224" "4649992" "4948388" "5070936" "5096465" "5120495" "5130771" "5382314" "5614320" "5642779" "5696665" "5719441" "5783316" "5786075" "5812570" "5895972" "6031285" "6167948" "6238454" "6264882" "6335863" "6337513" "6361857" "6390181" "6448642" "6517221" "6534792" "6538892").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/24 11:12
S37	6	"6507105"	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/24 11:19
S38	17	(low with expansion) and ((SiC or (silicon adj carbide)) with (grain and size)) and (Al or aluminum) and heat and (mean with grain with size)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/10 17:15